

MMBT3904

Rev.G Nov.-2020

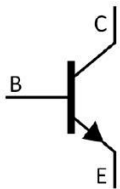
/ Descriptions

SOT-23 NPN Silicon NPN transistor in a SOT-23 Plastic Package.

/ Features

Low current, Low voltage, HF Product.

General purpose amplifier and switching.



PIN 1 Base PIN 2 Emitter PIN 3 Collector

/ h_{FE} Classifications & Marking

h_{FE} Range	100~300
Marking	• H1A

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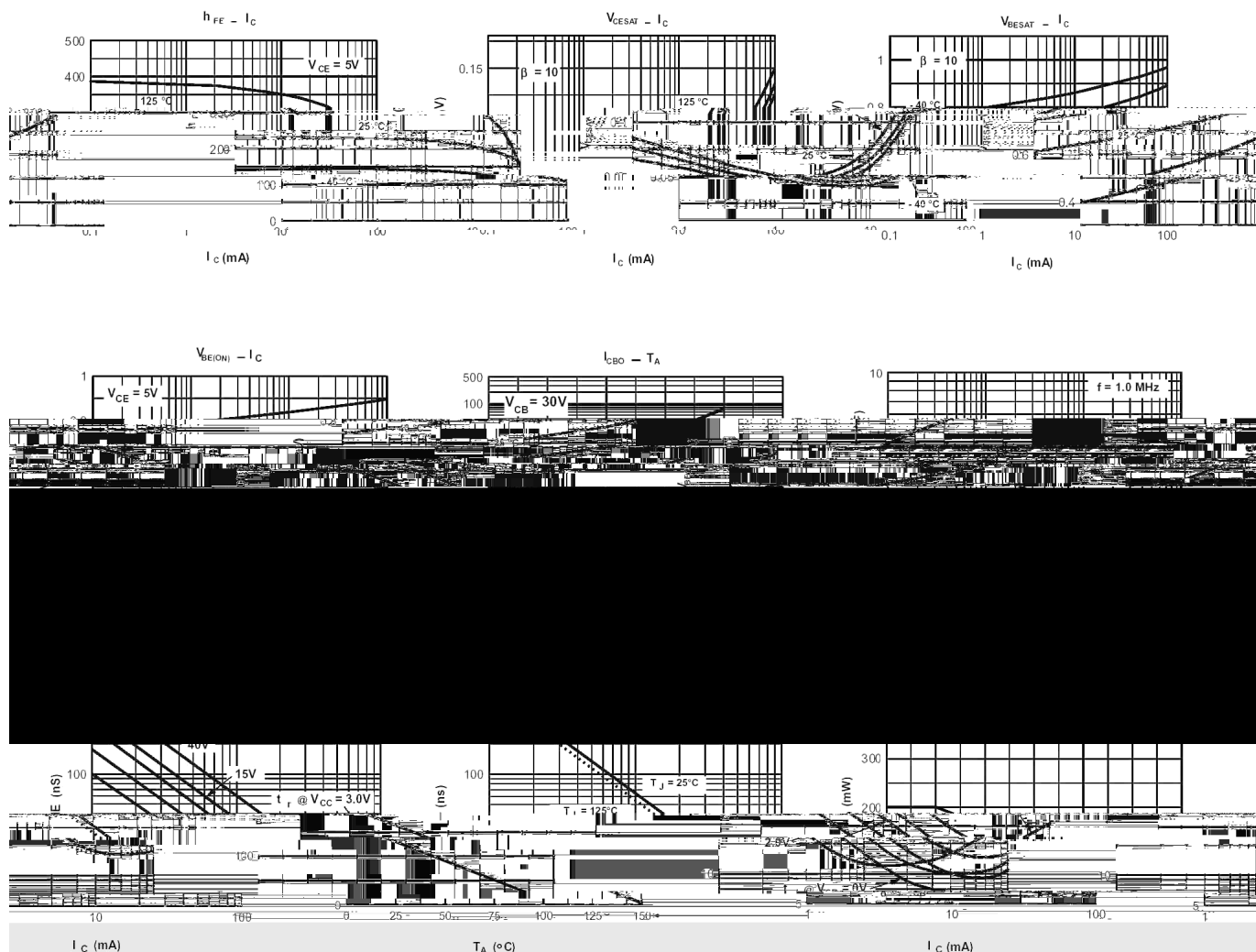
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	60	V
Collector to Emitter Voltage	V_{CEO}	40	V
Emitter to Base Voltage	V_{EBO}	6.0	V
Collector Current	I_C	200	mA
Collector Power Dissipation	P_C	200	mW
Collector Power Dissipation	$*P_C$	350	mW
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55~150	°C

* 7×5×0.6mm

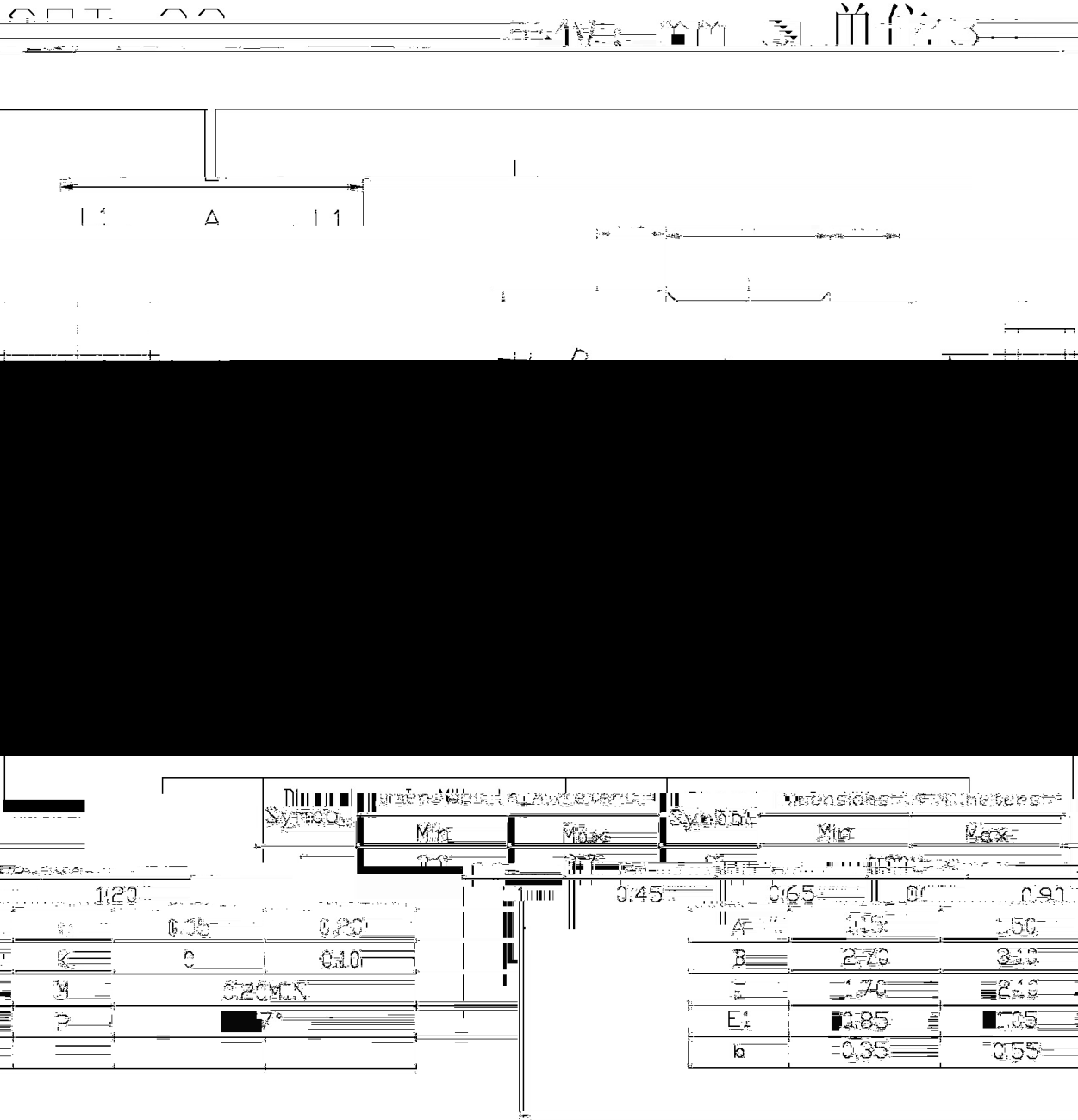
*When mounted on a 7×5×0.6mm ceramic board

Parameter	Symbol	Test Condition	Min	Typ	Unit
Collector to Base Breakdown Voltage	V_{CBR}	$I_C = 10\mu A$			V

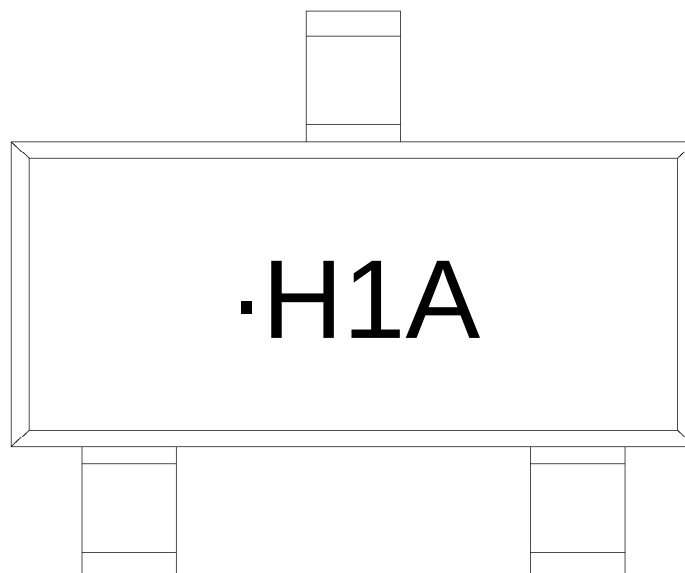
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



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H

1A

Note:

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Identify

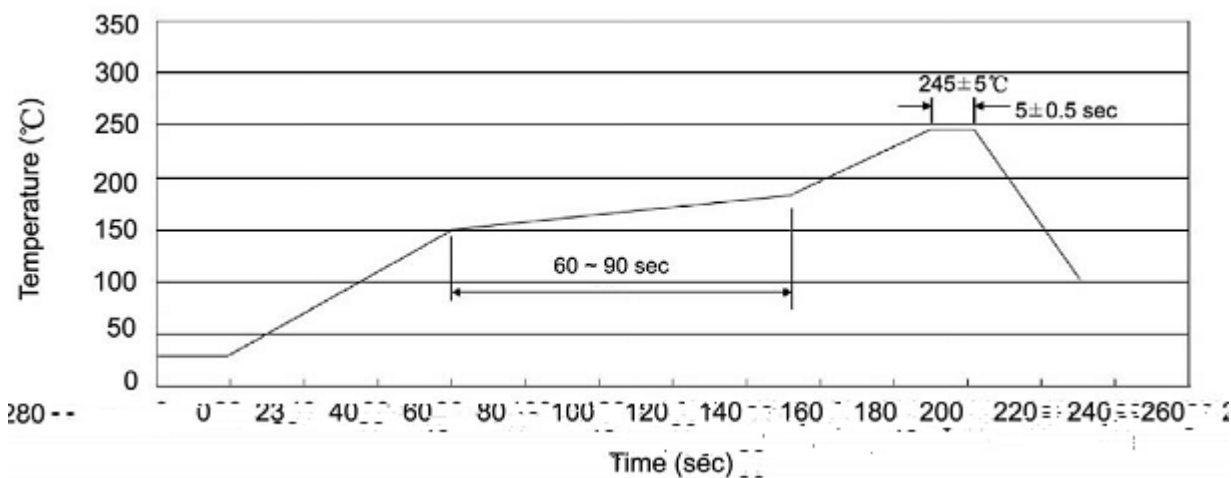
H

Company Code

1A

Product Type Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

/ Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

/ Packaging SPEC.

卷盘包装 / REEL

Package Type	Units	Dimension	(unit mm ³)
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